

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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ON Semiconductor®

FGD3325G2-F085

EcoSPARK®2 330mJ, 250V, N-Channel Ignition IGBT

Features

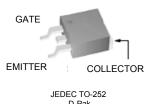
- SCIS Energy = 330mJ at T_J = 25°C
- Logic Level Gate Drive
- Qualified to AEC Q101
- RoHS Compliant

Applications

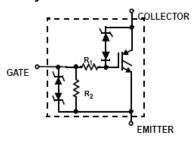
- Automotive Ignition Coil Driver Circuits
- Coil On Plug Applications



Package



Symbol



Absolute Maximum Ratings $T_A = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter		Ratings	Units
BV _{CER}	Collector to Emitter Breakdown Voltage (I _C = 1mA)		250	V
BV _{ECS}	Emitter to Collector Voltage - Reverse Battery Condition ($I_C = 10r$	28	V	
E _{SCIS25}	I_{SCIS} = 14.8A, L = 3.0mHy, R_{GE} = 1K Ω	330	mJ	
E _{SCIS150}	I_{SCIS} = 11.4A, L = 3.0mHy, R_{GE} = 1K Ω	195	mJ	
I _{C25}	Collector Current Continuous, at V _{GE} = 5.0V, T _C = 25°C	41	Α	
I _{C110}	Collector Current Continuous, at V _{GE} = 5.0V, T _C = 110°C	25	Α	
V_{GEM}	Gate to Emitter Voltage Continuous	±10	V	
D	Power Dissipation Total, at $T_C = 25^{\circ}C$ $T_C = 25^{\circ}C$		150	W
P_D	Power Dissipation Derating, for T _C > 25°C	T _C > 25°C	1.0	W/°C
T _J	Operating Junction Temperature Range	-55 to +175	°C	
T _{STG}	Storage Junction Temperature Range	-55 to +175	°C	
T _L	Max. Lead Temp. for Soldering (Leads at 1.6mm from case for 10s)		300	°C
T _{PKG}	Reflow soldering according to JESD020C		260	°C
ESD	HBM-Electrostatic Discharge Voltage at100pF, 1500Ω		4	kV
ESD	CDM-Electrostatic Discharge Voltage at 1Ω		2	kV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FGD3325G2	FGD3325G2-F085	TO252	330mm	16mm	2500 units

Electrical Characteristics $T_A = 25^{\circ}C$ unless otherwise noted

	Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
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Off State Characteristics

BV _{CER}	Collector to Emitter Breakdown Voltage	$I_{CE} = 2\text{mA}, V_{GE} = 0,$ $R_{GE} = 1\text{K}\Omega,$ $T_{J} = -40 \text{ to } 150^{\circ}\text{C}$		225	-	275	٧
BV _{CES}	Collector to Emitter Breakdown Voltage	$I_{CE} = 10 \text{mA}, V_{GE} = 0 \text{V},$ $R_{GE} = 0,$ $T_{J} = -40 \text{ to } 150^{\circ}\text{C}$		240	-	290	V
BV _{ECS}	Emitter to Collector Breakdown Voltage	$I_{CE} = -75 \text{mA}, V_{GE} = 0 \text{V},$ $T_{J} = 25 ^{\circ}\text{C}$		28	-	1	V
BV_{GES}	Gate to Emitter Breakdown Voltage	I _{GES} = ±2mA		±12	±14	-	V
1	I _{CER} Collector to Emitter Leakage Current	V_{CE} = 175V, R_{GE} = 1K Ω	$T_{J} = 25^{\circ}C$	1	1	25	μΑ
CER			$T_{\rm J} = 150^{\rm o}{\rm C}$	-	-	1	mA
ı	I _{ECS} Emitter to Collector Leakage Current	V _{EC} = 24V,	$T_{J} = 25^{\circ}C$	-	-	1	m۸
'ECS			$T_{J} = 150^{\circ}C$	-	-	40	mA
R ₁	Series Gate Resistance			-	120	-	Ω
R ₂	Gate to Emitter Resistance			10K	-	30K	Ω

On State Characteristics

V _{CE(SAT)}	Collector to Emitter Saturation Voltage	$I_{CE} = 6A, V_{GE} = 4V,$	$T_J = 25^{\circ}C$	-	1.15	1.25	V
V _{CE(SAT)}	Collector to Emitter Saturation Voltage	I_{CE} = 10A, V_{GE} = 4.5V,	$T_{\rm J} = 150^{\rm o}{\rm C}$	-	1.35	1.50	V
V _{CE(SAT)}	Collector to Emitter Saturation Voltage	$I_{CE} = 15A, V_{GE} = 4.5V,$	$T_{\rm J} = 150^{\rm o}{\rm C}$	1	1.68	1.85	V

Electrical Characteristics $T_A = 25^{\circ}C$ unless otherwise noted

Parameter

Dynam	ic Characteristics						
$Q_{G(ON)}$	Gate Charge	I _{CE} = 10A, V _{CE} = 12V, V _{GE} = 5V		-	21	-	nC
\/ ·	Gate to Emitter Threshold Voltage	I _{CE} = 1mA, V _{CE} = V _{GE}	$T_{\rm J} = 25^{\rm o}{\rm C}$	1.3	1.5	2.2	V
V _{GE(TH)} Gate to Emitter Threshold Voltage	I'CE - IIIIA, VCE - VGE,	$T_{\rm J} = 150^{\rm o}{\rm C}$	0.75	1.1	1.8	v	
V_{GEP}	Gate to Emitter Plateau Voltage	V _{CE} = 12V, I _{CE} = 10A		-	2.7	-	V

Test Conditions

Min

Max Units

Switching Characteristics

Symbol

t _{d(ON)R}	Current Turn-On Delay Time-Resistive	02 . 2	-	8.0	4	μS
t_{rR}	Current Rise Time-Resistive	$V_{GE} = 5V, R_G = 1K\Omega$ $T_J = 25^{\circ}C,$,	1.2	7	μS
t _{d(OFF)L}	Current Turn-Off Delay Time-Inductive			5.1	15	μS
t _{fL}	Current Fall Time-Inductive	$V_{GE} = 5V, R_{G} = 1K\Omega$ $I_{CE} = 6.5A, T_{J} = 25^{\circ}C,$	-	2.2	15	μS

Thermal Characteristics

R _{θJC} Thermal Resistance Junction to Case	-	-	1	°C/W	
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Typical Performance Curves

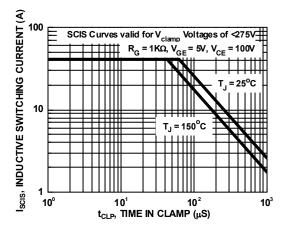


Figure 1. Self Clamped Inductive Switching Current vs. Time in Clamp

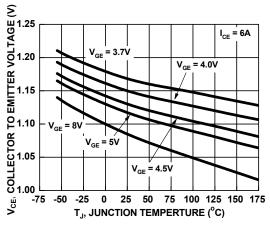


Figure 3. Collector to Emitter On-State Voltage vs. Junction Temperature

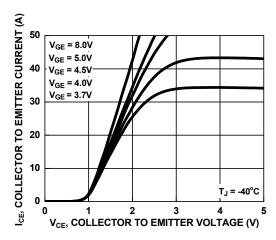


Figure 5. Collector to Emitter On-State Voltage vs. Collector Current

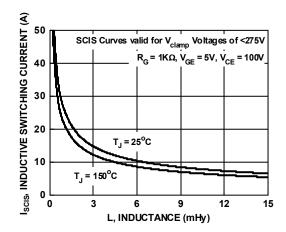


Figure 2. Self Clamped Inductive Switching Current vs. Inductance

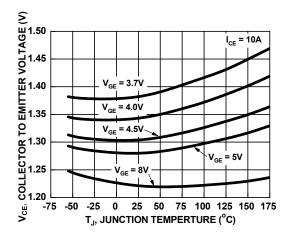


Figure 4. Collector to Emitter On-State Voltage vs. Junction Temperature

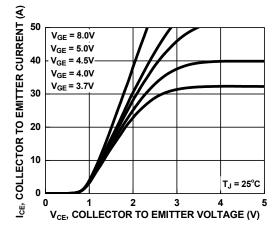


Figure 6. Collector to Emitter On-State Voltage vs. Collector Current

Typical Performance Curves (Continued)

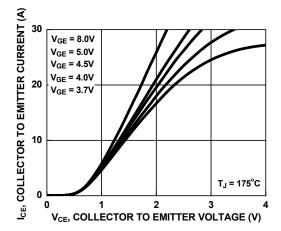


Figure 7. Collector to Emitter On-State Voltage vs. Collector Current

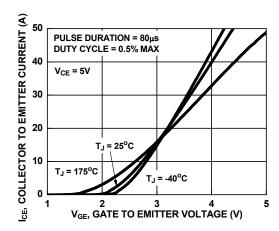


Figure 8. Transfer Characteristics

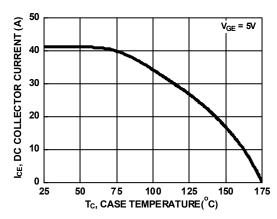


Figure 9. DC Collector Current vs. Case Temperature

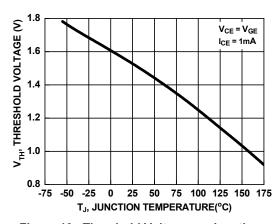


Figure 10. Threshold Voltage vs. Junction Temperature

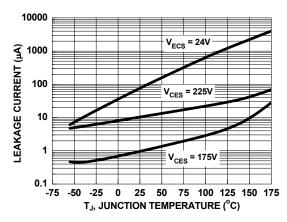


Figure 11. Leakage Current vs. Junction Temperature

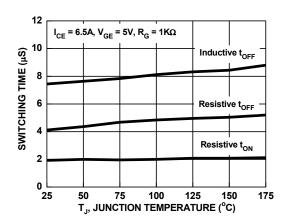
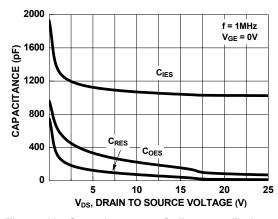


Figure 12. Switching Time vs. Junction Temperature

Typical Performance Curves (Continued)



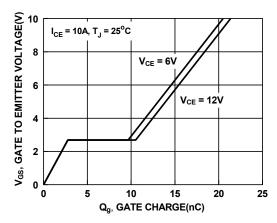


Figure 13. Capacitance vs. Collector to Emitter Voltage

Figure 14. Gate Charge

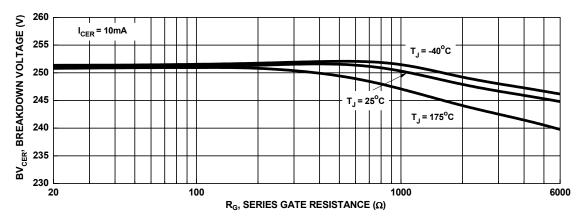


Figure 15. Break down Voltage vs. Series Gate Resistance

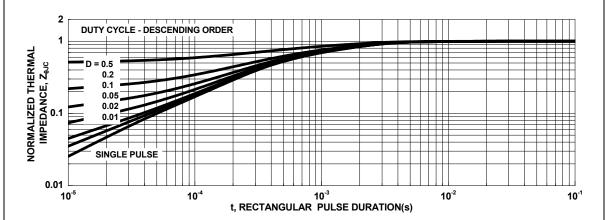


Figure 16. IGBT Normalized Transient Thermal Impedance, Junction to Case



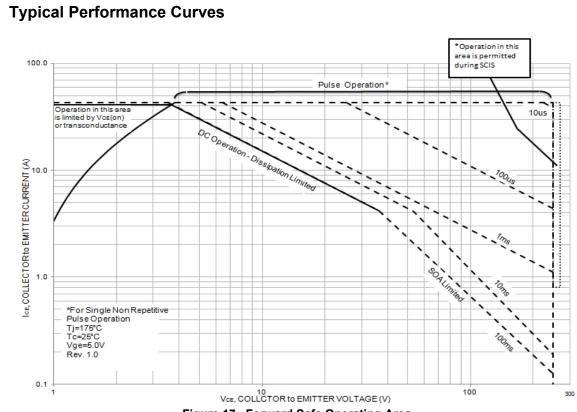
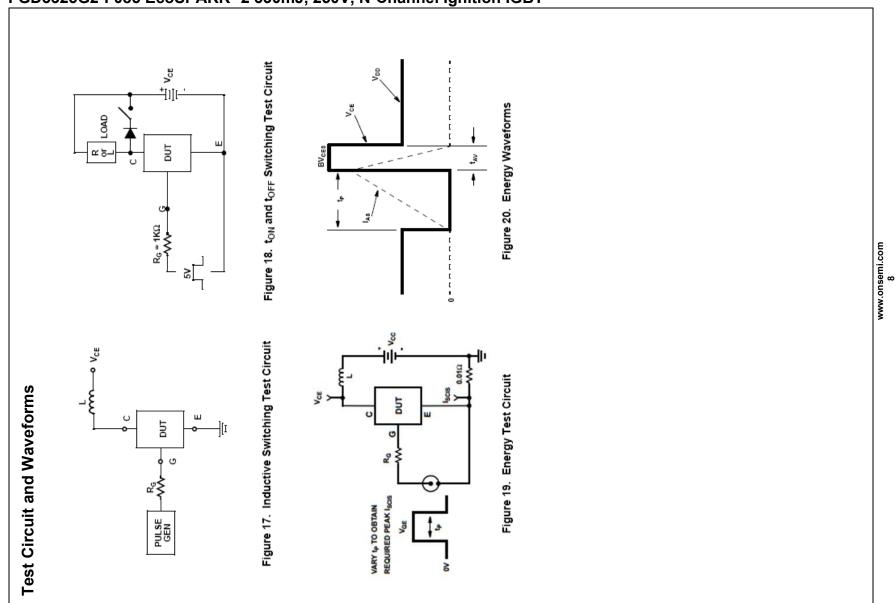
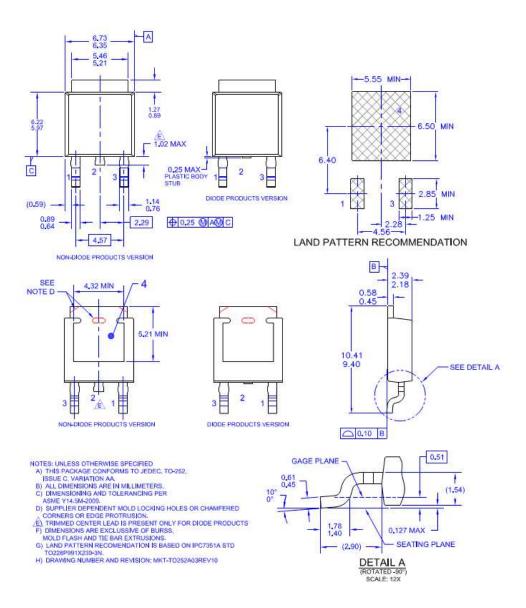


Figure 17. Forward Safe Operating Area



Mechanical Dimensions

D-PAK



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